

Title (en)
MULTIFUNCTION SENSOR AS POP MICROWAVE PCB

Title (de)
MULTIFUNKTIONSSENSOR ALS POP-MWLP

Title (fr)
CAPTEUR MULTIFONCTION EN TANT QUE POP-MWLP

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Application
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Abstract (en)
[origin: WO2012038127A1] The invention relates to a method for producing a component which comprises at least one micro-structured or nano-structured element (1). In the context of the method according to the invention, at least one micro-structured or nano-structured element (1) having at least one area (2) provided for making contact is applied to a carrier (3), wherein the element (1) is applied to the carrier (3) such that at least one area (2) of the element (1) that is provided for making contact adjoins the carrier (3). Subsequently, the element (1) is enveloped in an enveloping compound (4) and the element-enveloping compound composite (5) is detached from the carrier (3). Then, a first layer (6) comprising electrically conductive areas is applied to the side of the element-enveloping compound composite (5) that previously adjoined the carrier (3). Before, after or at the same time, at least one passage (7) is introduced into the enveloping compound (4). Subsequently, a conductor layer is applied to the surface of the passage (7) and at least to a section of the layer (6) comprising the first electrically conductive areas, such that the conductor layer (8) electrically contacts an area (2) provided for contacting, in order to generate a through contact (7), which enables space-saving contacting. The invention further relates to such a component.

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